ADS5122

# 8-Channel, 10-Bit, 65MSPS, 1.8V CMOS ANALOG-TO-DIGITAL CONVERTER 

## FEATURES

- 8 DIFFERENTIAL ANALOG INPUTS
- 1V ${ }^{\text {PP }}$ DIFFERENTIAL INPUT RANGE
- INT/EXT VOLTAGE REFERENCE
- ANALOG/DIGITAL SUPPLY: 1.8V
- DIGITAL I/O SUPPLY: 1.8V/3.3V
- DIFFERENTIAL NONLINEARITY: $\pm 0.4 L S B$
- INTEGRAL NONLINEARITY: $\pm 1.0 \mathrm{LSB}$
- SIGNAL-TO-NOISE: 59dB at $\mathrm{f}_{\mathrm{IN}}=\mathbf{2 0 M H z}$
- POWER DISSIPATION: 733mW
- INDIVIDUAL CHANNEL POWER-DOWN


## - 257-LEAD, 0.8 BALL PITCH, PLASTIC MicroSTAR BGA ${ }^{\text {TM }}$ ( $16 \mathrm{~mm} \cdot 16 \mathrm{~mm}$ )

## DESCRIPTION

The ADS5122 is a low-power, 8-channel, 10 -bit, 65MSPS CMOS Analog-to-Digital Converter (ADC) that operates from a single 1.8 V supply, while offering 1.8 V and 3.3 V digital $\mathrm{I} / \mathrm{O}$ flexibility. A single-ended input clock is used for simultaneous sampling of up to eight analog differential input channels. The flexible duty cycle adjust circuit (DCASEL) allows the use of a non- $50 \%$ clock duty cycle. Individual standby pins allow users the ability to power-down any number of ADCs
The internal reference can be bypassed to use an external reference to suit the accuracy and temperature drift requirements of the application. A 10 -bit parallel bus on eight channels is provided with 3 -state outputs.
The speed, resolution, and low power of the ADS5122 make it ideal for applications requiring high-density signal processing in low-power environments.
The ADS5122 is characterized for operation from $0^{\circ} \mathrm{C}$ to $70^{\circ} \mathrm{C}$.

## APPLICATIONS

- PORTABLE ULTRASOUND
- PORTABLE INSTRUMENTATION


Please be aware that an important notice concerning availability, standard warranty, and use in critical applications of Texas Instruments semiconductor products and disclaimers thereto appears at the end of this data sheet.

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ABSOLUTE MAXIMUM RATINGS ${ }^{(1)}$


NOTE: (1) Stresses above those listed under Absolute Maximum Ratings may cause permanent damage to the device. Exposure to absolute maximum conditions for extended periods may affect device reliability.

This integrated circuit can be damaged by ESD. Texas Instruments recommends that all integrated circuits be handled with appropriate precautions. Failure to observe proper handling and installation procedures can cause damage.
ESD damage can range from subtle performance degradation to complete device failure. Precision integrated circuits may be more susceptible to damage because very small parametric changes could cause the device not to meet its published specifications.

PACKAGE/ORDERING INFORMATION ${ }^{(1)}$

| PRODUCT | PACKAGE-LEAD | SPECIFIED <br> PESIGNATOR | TEMPERATURE <br> RANGE | PACKAGE <br> MARKING | ORDERING <br> NUMBER | TRANSPORT <br> MEDIA, QUANTITY |
| :--- | :---: | :---: | :---: | :---: | :---: | :---: |
| ADS5122 | MicroSTAR BGA-257 | GHK | $0^{\circ} \mathrm{C}$ to $+70^{\circ} \mathrm{C}$ | ADS5122CGHK | ADS5122CGHK | Tray, 90 |

NOTE: (1) For the most current package and ordering information, see the Package Option Addendum located at the end of this data sheet.

## BLOCK DIAGRAM



## DC CHARACTERISTICS

$A V_{D D}=D V_{D D}=1.8 \mathrm{~V}, D R V_{D D}=3.3 \mathrm{~V}$, Clock $=65 \mathrm{MSPS}, 50 \%$ Clock Duty Cycle, -0.5 dBFS Input Span, Internal Reference, $\mathrm{I}_{\mathrm{REFR}}=4.42 \mathrm{k} \Omega, \mathrm{T}_{\mathrm{MIN}}=0^{\circ} \mathrm{C}, \mathrm{T}_{\mathrm{MAX}}=+70^{\circ} \mathrm{C}$, and typical values at $T_{A}=25^{\circ} \mathrm{C}$, unless otherwise noted.

| PARAMETER | CONDITION | ADS5122 |  |  | UNITS |
| :---: | :---: | :---: | :---: | :---: | :---: |
|  |  | MIN | TYP | MAX |  |
| RESOLUTION |  |  | 10 |  | Bits |
| DC ACCURACY <br> Differential Nonlinearity (DNL) Integral Nonlinearity (INL) <br> No Missing Codes <br> Gain Error <br> Offset Error <br> Gain Temperature Coefficient <br> Gain Matching | External Reference External Reference | $\begin{aligned} & -0.9 \\ & -2.5 \\ & -1.0 \end{aligned}$ | $\begin{gathered} \pm 0.4 \\ \pm 1.0 \\ \text { Tested } \\ 0.1 \\ 0.2 \\ 6 \\ \pm 0.7 \end{gathered}$ | $\begin{aligned} & +1.0 \\ & +2.5 \\ & +1.0 \\ & +2.5 \end{aligned}$ | LSB LSB <br> \%FSR <br> \%FSR <br> ppm $/{ }^{\circ} \mathrm{C}$ <br> \%FSR |
| ANALOG INPUT <br> Input Voltage Range (AIN+, AIN-) Input Voltage, Differential Full-Scale Input Common-Mode Range <br> Input Resistance, $\mathrm{R}_{\mathrm{IN}}$ <br> Input Capacitance, $\mathrm{C}_{\text {IN }}$ | $\mathrm{f}_{\text {CLK }}=65 \mathrm{MSPS}$ | REFB | $\begin{gathered} 1 \\ =\mathrm{T}+\mathrm{REF} \\ 20 \\ 5 \\ \hline \end{gathered}$ | REFT | $\begin{gathered} \mathrm{V} \\ \mathrm{~V} \text { Pp } \\ \mathrm{V} \\ \mathrm{k} \Omega \\ \mathrm{pF} \\ \hline \end{gathered}$ |
| INTERNAL REFERENCE VOLTAGES <br> Reference, Top (REFT) <br> Reference, Bottom (REFB) <br> Int Reference Temperature Coefficient |  | $\begin{aligned} & 1.30 \\ & 0.76 \end{aligned}$ | $\begin{gathered} 1.35 \\ 0.82 \\ 10 \\ \hline \end{gathered}$ | $\begin{aligned} & 1.42 \\ & 0.87 \end{aligned}$ |  |
| EXTERNAL REFERENCE GENERATION <br> Reference, Top (REFT) <br> Reference, Bottom (REFB) <br> Input Resistance, REFR $_{\text {IN }}$ <br> (between REFB and REFT) |  | $\begin{aligned} & 1.15 \\ & 0.65 \end{aligned}$ | $\begin{gathered} 1.25 \\ 0.75 \\ 80 \end{gathered}$ | $\begin{aligned} & 1.35 \\ & 0.85 \end{aligned}$ | $\begin{aligned} & \mathrm{V} \\ & \mathrm{~V} \\ & \Omega \end{aligned}$ |
| POWER SUPPLY <br> Operating Supply Current, $\mathrm{I}_{\mathrm{DD}}$ <br> Analog Operating Supply Current, IAV $V_{D D}$ <br> Digital Operating Supply Current, IDV ${ }_{D D}$ <br> Driver Operating Supply Current, IDRV ${ }_{\text {DD }}$ <br> Operating Voltage <br> $A V_{D D}$ <br> $D V_{D D}$ <br> DRV ${ }_{D D}$ <br> Power-Dissipation <br> Power Standby <br> Power-Supply Rejection Ratio, PSRR | $\mathrm{f}_{\mathrm{IN}}=3.5 \mathrm{MHz}$ $\begin{aligned} & \mathrm{C}_{\mathrm{L}}=20 \mathrm{pF}, 3.3 \mathrm{~V} \\ & \mathrm{C}_{\mathrm{L}}=20 \mathrm{pF}, 1.8 \mathrm{~V} \end{aligned}$ $\begin{gathered} \mathrm{DRV}_{\mathrm{DD}}=3.3 \mathrm{~V} \\ \mathrm{DRV}=1.8 \mathrm{~V} \\ \text { CLK Running } \\ \text { CLK Stopped } \end{gathered}$ $\pm 5 \%, A V_{D D}$ | $\begin{aligned} & 1.65 \\ & 1.65 \\ & 1.65 \end{aligned}$ | $\begin{gathered} 357 \\ 226 \\ 64 \\ 60 \\ 31 \\ \\ 1.8 \\ 1.8 \\ 1.8 \\ 733 \\ 590 \\ 68 \\ 54 \\ 14 \\ 1.6 \\ 5 \end{gathered}$ | $\begin{gathered} 375 \\ 245 \\ 74 \\ 70 \\ 40 \\ 2.0 \\ 2.0 \\ 3.6 \\ 800 \\ 615 \end{gathered}$ | mA <br> mA <br> mA <br> mA <br> mA <br> V <br> V <br> V <br> mW <br> mW <br> mW <br> mW <br> mW <br> mW <br> $\mathrm{mV} / \mathrm{V}$ |

## DC CHARACTERISTICS

$A V_{D D}=D V_{D D}=1.8 \mathrm{~V}, D R V_{D D}=3.3 \mathrm{~V}$, Clock $=65 \mathrm{MSPS}, 50 \%$ Clock Duty Cycle, -0.5 dBFS Input Span, Internal Reference, and $\mathrm{T}_{\text {MIN }}$ to $\mathrm{T}_{\mathrm{MAX}}$, unless otherwise noted.

| PARAMETER | CONDITION | ADS5122 |  |  | UNITS |
| :---: | :---: | :---: | :---: | :---: | :---: |
|  |  | MIN | TYP | MAX |  |
| DIGITAL INPUTS ( $\overline{\mathrm{STBY}} \mathrm{A}-\mathrm{H}$, PDREF, $\overline{\mathrm{OE}, ~ C L K)}$ <br> High-Level Input Voltage, $\mathrm{V}_{\mathrm{H}}$ <br> Low-Level Input Voltage, $\mathrm{V}_{\text {IL }}$ <br> High-Level Input Current, $\mathrm{I}_{\mid \mathrm{H}}$ <br> Low-Level Input Current, $\mathrm{I}_{\mathrm{L}}$ | $\begin{gathered} \mathrm{DRV}_{\mathrm{DD}}=3.3 \mathrm{~V} / 1.8 \mathrm{~V} \\ \mathrm{~V}_{\mathrm{IH}}=\mathrm{DRV} \mathrm{~V}_{\mathrm{DD}} \\ \mathrm{~V}_{\mathrm{IL}}=0 \mathrm{~V} \end{gathered}$ | $0.70 \cdot \mathrm{DRV}_{\mathrm{DD}}$ |  | $\begin{gathered} 0.25 \cdot \text { DRV }_{\mathrm{DD}} \\ \pm 1 \\ \pm 1 \end{gathered}$ | V <br> V <br> $\mu \mathrm{A}$ <br> $\mu \mathrm{A}$ |
| DIGITAL INPUTS (DCASEL) <br> High-Level Input Voltage, $\mathrm{V}_{\mathrm{IH}}$ Low-Level Input Voltage, $\mathrm{V}_{\text {IL }}$ High-Level Input Current, $\mathrm{I}_{\mathrm{IH}}$ Low-Level Input Current, ILL | $\begin{gathered} \mathrm{V}_{\mathrm{IH}}=\mathrm{DV} \mathrm{VDD}_{\mathrm{DD}} \\ \mathrm{~V}_{\mathrm{IL}}=0 \mathrm{~V} \end{gathered}$ | $0.70 \cdot \mathrm{DV}_{\text {DD }}$ |  | $\begin{gathered} 0.25 \cdot \mathrm{DV}_{\mathrm{DD}} \\ \pm 1 \\ \pm 1 \end{gathered}$ | $\begin{gathered} \mathrm{V} \\ \mathrm{~V} \\ \mu \mathrm{~A} \\ \mu \mathrm{~A} \end{gathered}$ |
| $\begin{aligned} & \text { DIGITAL OUTPUTS }\left(\mathrm{DRV}_{\mathrm{DD}}=3.3 / 1.8 \mathrm{~V}\right) \\ & \text { High-Level Output Voltage, } \mathrm{V}_{\mathrm{OH}} \\ & \text { Low-Level Output Voltage, } \mathrm{V}_{\mathrm{OL}} \\ & \text { External Load Capacitance, } \mathrm{C}_{\mathrm{L}} \\ & \text { 3-State Leakage Current, } \mathrm{I}_{\mathrm{LEAK}} \end{aligned}$ | $\begin{aligned} & \mathrm{I}_{\mathrm{OH}}=-50 \mu \mathrm{~A} \\ & \mathrm{I}_{\mathrm{OL}}=50 \mu \mathrm{~A} \\ & \overline{\mathrm{OE}}=\mathrm{HIGH} \end{aligned}$ | $0.8 \cdot \mathrm{DRV}_{\text {DD }}$ | 15 | $\begin{gathered} 0.2 \cdot \mathrm{DRV}_{\mathrm{DD}} \\ \pm 1 \end{gathered}$ | $\begin{gathered} \mathrm{V} \\ \mathrm{~V} \\ \mathrm{pF} \\ \mu \mathrm{~A} \end{gathered}$ |

## AC CHARACTERISTICS

$\mathrm{AV}_{\mathrm{DD}}=\mathrm{DV}_{\mathrm{DD}}=1.8 \mathrm{~V}, \mathrm{DRV}_{\mathrm{DD}}=3.3 \mathrm{~V}, 50 \%$ Clock Duty Cycle, CLK $=65 \mathrm{MSPS}$, Analog Input at -0.5 dBFS Input Span, Internal Voltage Reference, $\mathrm{T}_{\mathrm{MIN}}=0^{\circ} \mathrm{C}$, $\mathrm{T}_{\text {MAX }}=70^{\circ} \mathrm{C}$, and typical values at $\mathrm{T}_{\mathrm{A}}=25^{\circ} \mathrm{C}$, unless otherwise noted.

| PARAMETER | CONDITION | ADS5122 |  |  | UNITS |
| :---: | :---: | :---: | :---: | :---: | :---: |
|  |  | MIN | TYP | MAX |  |
| Signal-to-Noise Ratio (SNR) | $\begin{aligned} \mathrm{f}_{\mathrm{IN}} & =3.5 \mathrm{MHz} \\ \mathrm{f}_{\mathrm{N}} & =10 \mathrm{MHz} \\ \mathrm{f}_{\mathrm{IN}} & =20 \mathrm{MHz} \end{aligned}$ | $\begin{aligned} & 56 \\ & 56 \end{aligned}$ | $\begin{aligned} & 59 \\ & 59 \\ & 59 \end{aligned}$ |  | dB <br> dB <br> dB |
| Signal-to-Noise and Distortion (SINAD) | $\begin{aligned} \mathrm{f}_{\mathrm{IN}} & =3.5 \mathrm{MHz} \\ \mathrm{f}_{\mathrm{N}} & =10 \mathrm{MHz} \\ \mathrm{f}_{\mathbb{N}} & =20 \mathrm{MHz} \end{aligned}$ | $\begin{aligned} & \hline 56 \\ & 56 \end{aligned}$ | $\begin{aligned} & 58 \\ & 58 \\ & 58 \end{aligned}$ |  | $\begin{aligned} & \mathrm{dB} \\ & \mathrm{~dB} \\ & \mathrm{~dB} \end{aligned}$ |
| Effective Number of Bits (ENOB) | $\begin{aligned} & \mathrm{f}_{\mathrm{IN}}=3.5 \mathrm{MHz} \\ & \mathrm{f}_{\mathrm{IN}}=10 \mathrm{MHz} \\ & \mathrm{f}_{\mathrm{IN}}=20 \mathrm{MHz} \end{aligned}$ | $\begin{aligned} & 9.0 \\ & 9.0 \end{aligned}$ | $\begin{aligned} & \hline 9.3 \\ & 9.3 \\ & 9.3 \end{aligned}$ |  | Bits <br> Bits <br> Bits |
| Spurious-Free Dynamic Range (SFDR) | $\begin{aligned} \mathrm{f}_{\mathrm{IN}} & =3.5 \mathrm{MHz} \\ \mathrm{f}_{\mathrm{N}} & =10 \mathrm{MHz} \\ \mathrm{f}_{\mathbb{N}} & =20 \mathrm{MHz} \end{aligned}$ | $\begin{aligned} & 65 \\ & 65 \end{aligned}$ | $\begin{aligned} & 72 \\ & 72 \\ & 68 \end{aligned}$ |  | dBc <br> dBc <br> dBc |
| 2nd-Harmonic Distortion (HD2) | $\begin{aligned} & \mathrm{f}_{\mathrm{IN}}=3.5 \mathrm{MHz} \\ & \mathrm{f}_{\mathrm{IN}}=10 \mathrm{MHz} \\ & \mathrm{f}_{\mathrm{IN}}=20 \mathrm{MHz} \end{aligned}$ | $\begin{aligned} & 68 \\ & 68 \end{aligned}$ | $\begin{aligned} & \hline 83 \\ & 79 \\ & 79 \end{aligned}$ |  | dBc <br> dBc <br> dBc |
| 3rd-Harmonic Distortion (HD3) | $\begin{aligned} \mathrm{f}_{\mathrm{IN}} & =3.5 \mathrm{MHz} \\ \mathrm{f}_{\mathrm{IN}} & =10 \mathrm{MHz} \\ \mathrm{f}_{\mathrm{IN}} & =20 \mathrm{MHz} \end{aligned}$ | $\begin{aligned} & 65 \\ & 65 \end{aligned}$ | $\begin{aligned} & 72 \\ & 72 \\ & 68 \end{aligned}$ |  | $\begin{aligned} & \mathrm{dBc} \\ & \mathrm{dBc} \\ & \mathrm{dBc} \end{aligned}$ |
| 2-Tone Intermodulation Distortion (IMD) <br> Channel-to-Channel Crosstalk  <br> Effective Resolution Bandwidth  <br> Over-Voltage Recovery Time ${ }^{(1)}$  <br> Differential Gain  <br> Differential Phase ${ }^{(1)}$  | $\begin{gathered} \mathrm{f}_{1}=4.43 \mathrm{MHz}, \mathrm{f}_{2}=4.53 \mathrm{MHz} \text { at }-6.5 \mathrm{~dB} \\ \mathrm{f}_{\mathrm{IN}}=10 \mathrm{MHz}, \mathrm{DRV}_{\mathrm{DD}}=3.3 \mathrm{~V} \end{gathered}$ |  | $\begin{gathered} \hline-69 \\ 89 \\ 30 \\ 20 \\ \pm 1 \\ \pm 0.25 \end{gathered}$ |  | dBFS dB MHz ns $\%$ Degrees |

NOTE: (1) Assured by design.

## SWITCHING CHARACTERISTICS

$\mathrm{AV}_{\mathrm{DD}}=\mathrm{DV}_{\mathrm{DD}}=1.8 \mathrm{~V}, \mathrm{DRV}_{\mathrm{DD}}=3.3 \mathrm{~V}, 50 \%$ Clock Duty Cycle, CLK $=65 \mathrm{MSPS}$, Analog Input at -0.5 dBFS Input Span, Internal Voltage Reference, $\mathrm{T}_{\mathrm{MIN}}=0^{\circ} \mathrm{C}$, and $\mathrm{T}_{\mathrm{MAX}}=70^{\circ} \mathrm{C}$. Typical values at $\mathrm{T}_{\mathrm{A}}=25^{\circ} \mathrm{C}$, unless otherwise noted.

| PARAMETER | CONDITION | ADS5122 |  |  | UNITS |
| :---: | :---: | :---: | :---: | :---: | :---: |
|  |  | MIN | TYP | MAX |  |
| Maximum Conversion Rate <br> Clock Duty Cycle <br> Data Latency ${ }^{(1)}$ <br> Clock $\downarrow$ to Data Valid $\mathrm{t}_{\mathrm{DO}}{ }^{(1)}$ <br> $\overline{\mathrm{OE}} \downarrow$ to Outputs Enabled $t_{E N}{ }^{(1)}$ <br> $\overline{\mathrm{OE}} \uparrow$ Rising to Outputs Tri-Stated <br> Aperture Delay <br> Aperture Uncertainty (Jitter) | DCASEL Enabled | 5 | $\begin{gathered} 30 \text { to } 70 \\ 6.5 \\ 8 \\ 8 \\ 8 \\ 1 \\ 2 \end{gathered}$ | 65 10 |  |

TIMING DIAGRAM (Per ADC Channel)


PIN CONFIGURATION


PIN DESCRIPTIONS

| NAME | PINS | I/O | TERMINAL DESCRIPTION |
| :---: | :---: | :---: | :---: |
| $\mathrm{AV}_{\mathrm{DD}}$ | C6, C7, E6, F1, F2, F3, F5, F6, J6, N3, P3, P5, P6, P7, R6, V6, W6 | 1 | Analog Supply (1.8V) |
| AGND | A3, A5, B5, B9, C1, C5, C9, E3, E7, F7, G1, G5, G6, H6, J1, J2, M2, N5, N6, P8, R1, R2, R3, R7, U1, U5, U10, V5, V10, W3, W7 | 1 | Analog Ground |
| AINA+ | U7 | 1 | Analog Input Channel A |
| AINA- | V7 | 1 | Complementary Analog Input Channel A |
| AINB+ | W4 | 1 | Analog Input Channel B |
| AINB- | V4 | 1 | Complementary Analog Input Channel B |
| AINC+ | T1 | 1 | Analog Input Channel C |
| AINC- | T2 | 1 | Complementary Analog Input Channel C |
| AIND+ | P2 | 1 | Analog Input Channel D |
| AIND- | P1 | 1 | Complementary Analog Input Channel D |
| AINE+ | G3 | 1 | Analog Input Channel E |
| AINE- | G2 | 1 | Complementary Analog Input Channel E |
| AINF+ | D1 | 1 | Analog Input Channel F |
| AINF- | D2 | 1 | Complementary Analog Input Channel F |
| AING+ | A4 | 1 | Analog Input Channel G |
| AING- | B4 | I | Complementary Analog Input Channel G |
| AlNH+ | B6 |  | Analog Input Channel H |
| AlNH- | A6 | 1 | Complementary Analog Input Channel H |
| CLK | W9 | 1 | Clock Input |
| REFT | K3, L1, J3 | I/O | Reference Top |
| REFB | K5, J5, L5 | I/O | Reference Bottom |
| CML | L2, L3 | O | Common-Mode Level Output |
| BG | K1 | 1/O | Bandgap Decoupling (Decouple with $0.1 \mu \mathrm{~F}$ cap to AGND) |
| IREFR | K6 | 1 | Internal Reference Bias Current (Connect 4.42k $\Omega$ resistor from this pin AGND to set internal bias amplifier current.) |
| DNC | L6 | 1 | Do Not Connect |
| DNC | M1 | 1 | Do Not Connect |
| NC | E1, E2, E5, K2, U6, W5 | 1 | No Internal Connection |
| DCASEL | N2 | 1 | Duty Cycle Adjust |
| DV ${ }_{\text {D }}$ | C2, C3, C4, D3, E8, F8, H3, H5, M3, M5, R8, T3, U3, U4, U8, V3, P13, R13 P17, L15, J14, F17, F12, E12 | 1 | Digital Supply (1.8V) |
| DGND | A2, A7, B1, B2, B3, B7, B13, C13, G15, H1, H2, H17, L17, M6, N1, N15, U2, U13, U14, V1, V2, V8, W2, W8 | I | Digital Ground |
| PDREF | V9 | 1 | Power-Down Ref: 0 = internal reference, 1 = external reference. In external reference mode connect REFT to BG pin. |
| $\overline{\text { STBY }}$ A | W10 | 1 | Power-Down Channel A |
| STBY B | P9 | 1 | Power-Down Channel B |
| STBY C | R9 | 1 | Power-Down Channel C |
| STBY D | U9 | 1 | Power-Down Channel D |
| STBY E | C8 | 1 | Power-Down Channel E |
| $\overline{\text { STBY }} \mathrm{F}$ | B8 | 1 | Power-Down Channel F |
| STBY G | A8 | 1 | Power-Down Channel G |
| $\overline{\text { STBY }} \mathrm{H}$ | A9 | 1 | Power-Down Channel H |
| $\overline{\mathrm{OE}}$ | P10 | 1 | Enable all Digital Outputs, Ch. A-H. $\overline{\mathrm{OE}}: 0=$ Outputs Enable. $\overline{\mathrm{OE}}: 1$ = Outputs disabled (3-state). |
| DRV DD | B17, C16, D17, E9, E10, E11, E17, F9, H14, H15, K17, L14, N14, P12, P14, P15 R10, R12, R14 | 1 | Driver Digital Supply ( 1.8 V or 3.3 V ) |
| DRGND | E13, F10, F11, F13, F14, F15, G14, G17, M14, M15, M17, N17, U11, U12, U15, U16 | 1 | Driver Digital Ground |


| NAME | PINS | I/O | TERMINAL DESCRIPTION | NAME | PINS | I/O | TERMINAL DESCRIPTION |
| :---: | :---: | :---: | :---: | :---: | :---: | :---: | :---: |
| D0A | V14 | O | Bit 1, Channel A (LSB) | D0E | F18 | O | Bit 1, Channel E (LSB) |
| D1A | W14 | 0 | Bit 2, Channel A | D1E | F19 | O | Bit 2, Channel E |
| D2A | V13 | 0 | Bit 3, Channel A | D2E | G18 | O | Bit 3, Channel E |
| D3A | W13 | 0 | Bit 4, Channel A | D3E | G19 | O | Bit 4, Channel E |
| D4A | V12 | 0 | Bit 5, Channel A | D4E | H18 | 0 | Bit 5, Channel E |
| D5A | W12 | 0 | Bit 6, Channel A | D5E | H19 | 0 | Bit 6, Channel E |
| D6A | R11 | 0 | Bit 7, Channel A | D6E | J15 | O | Bit 7, Channel E |
| D7A | P11 | 0 | Bit 8, Channel A | D7E | J17 | O | Bit 8, Channel E |
| D8A | V11 | 0 | Bit 9, Channel A | D8E | J18 | O | Bit 9, Channel E |
| D9A | W11 | 0 | Bit 10, Channel A (MSB) | D9E | J19 | O | Bit 10, Channel E (MSB) |
| D0B | V19 | 0 | Bit 1, Channel B (LSB) | D0F | A18 | O | Bit 1, Channel F (LSB) |
| D1B | V18 | 0 | Bit 2, Channel B | D1F | B18 | O | Bit 2, Channel F |
| D2B | U17 | 0 | Bit 3, Channel B | D2F | C17 | O | Bit 3, Channel F |
| D3B | W18 | 0 | Bit 4, Channel B | D3F | B19 | O | Bit 4, Channel F |
| D4B | V17 | O | Bit 5, Channel B | D4F | C18 | 0 | Bit 5, Channel F |
| D5B | W17 | 0 | Bit 6, Channel B | D5F | C19 | 0 | Bit 6, Channel F |
| D6B | V16 | 0 | Bit 7, Channel B | D6F | D18 | O | Bit 7, Channel F |
| D7B | W16 | 0 | Bit 8, Channel B | D7F | D19 | O | Bit 8, Channel F |
| D8B | V15 | 0 | Bit 9, Channel B | D8F | E18 | O | Bit 9, Channel F |
| D9B | W15 | 0 | Bit 10, Channel B (MSB) | D9F | E19 | 0 | Bit 10, Channel F (MSB) |
| D0C | P19 | 0 | Bit 1, Channel C (LSB) | DOG | A14 | 0 | Bit 1, Channel G (LSB) |
| D1C | P18 | 0 | Bit 2, Channel C | D1G | B14 | 0 | Bit 2, Channel G |
| D2C | R19 | 0 | Bit 3, Channel C | D2G | C14 | O | Bit 3, Channel G |
| D3C | R18 | 0 | Bit 4, Channel C | D3G | A15 | O | Bit 4, Channel G |
| D4C | R17 | 0 | Bit 5, Channel C | D4G | B15 | O | Bit 5, Channel G |
| D5C | T19 | 0 | Bit 6, Channel C | D5G | E14 | 0 | Bit 6, Channel G |
| D6C | T18 | 0 | Bit 7, Channel C | D6G | C15 | O | Bit 7, Channel G |
| D7C | U19 | 0 | Bit 8, Channel C | D7G | A16 | 0 | Bit 8, Channel G |
| D8C | U18 | 0 | Bit 9, Channel C | D8G | B16 | 0 | Bit 9, Channel G |
| D9C | T17 | 0 | Bit 10, Channel C (MSB) | D9G | A17 | O | Bit 10, Channel G (MSB) |
| DOD | K14 | 0 | Bit 1, Channel D (LSB) | DOH | C10 | O | Bit 1, Channel H (LSB) |
| D1D | K15 | 0 | Bit 2, Channel D | D1H | B10 | O | Bit 2, Channel H |
| D2D | K18 | 0 | Bit 3, Channel D | D2H | A10 | 0 | Bit 3, Channel H |
| D3D | K19 | 0 | Bit 4, Channel D | D3H | C11 | 0 | Bit 4, Channel H |
| D4D | L18 | 0 | Bit 5, Channel D | D4H | B11 | O | Bit 5, Channel H |
| D5D | L19 | 0 | Bit 6, Channel D | D5H | A11 | 0 | Bit 6, Channel H |
| D6D | M19 | 0 | Bit 7, Channel D | D6H | A12 | O | Bit 7, Channel H |
| D7D | M18 | 0 | Bit 8, Channel D | D7H | B12 | 0 | Bit 8, Channel H |
| D8D | N19 | 0 | Bit 9, Channel D | D8H | C12 | 0 | Bit 9, Channel H |
| D9D | N18 | 0 | Bit 10, Channel D (MSB) | D9H | A13 | 0 | Bit 10, Channel H (MSB) |

## TYPICAL CHARACTERISTICS

$T_{A}=25^{\circ} \mathrm{C}, A V_{D D}=D V_{D D}=1.8 \mathrm{~V}, D R V_{D D}=3.3 \mathrm{~V}, \mathrm{f}_{\mathrm{IN}}=-0.5 \mathrm{dBFS}$, Internal Reference, Clock $=65 \mathrm{MSPS}$, and Differential Input Range $=1 \mathrm{~V}_{\mathrm{PP}}$, unless otherwise noted.







## TYPICAL CHARACTERISTICS (Cont.)

$T_{A}=25^{\circ} \mathrm{C}, A V_{D D}=D V_{D D}=1.8 \mathrm{~V}, D R V_{D D}=3.3 \mathrm{~V}, \mathrm{f}_{\mathrm{IN}}=-0.5 \mathrm{dBFS}$, Internal Reference, Clock $=65 \mathrm{MSPS}$, and Differential Input Range $=1 \mathrm{~V}_{\mathrm{PP}}$, unless otherwise noted.







## TYPICAL CHARACTERISTICS (Cont.)

$\mathrm{T}_{\mathrm{A}}=25^{\circ} \mathrm{C}, A \mathrm{~V}_{\mathrm{DD}}=\mathrm{DV} \mathrm{DD}=1.8 \mathrm{~V}, \mathrm{DRV} \mathrm{DD}=3.3 \mathrm{~V}, \mathrm{f}_{\mathrm{IN}}=-0.5 \mathrm{dBFS}$, Internal Reference, Clock $=65 \mathrm{MSPS}$, and Differential Input Range $=1 \mathrm{~V}_{\mathrm{PP}}$, unless otherwise noted.




DYNAMIC PERFORMANCE vs CLOCK DUTY CYCLE



## TYPICAL CHARACTERISTICS (Cont.)

$\mathrm{T}_{\mathrm{A}}=25^{\circ} \mathrm{C}, \mathrm{AV}_{\mathrm{DD}}=\mathrm{DV} \mathrm{DD}=1.8 \mathrm{~V}, \mathrm{DRV} \mathrm{DD}=3.3 \mathrm{~V}, \mathrm{f}_{\mathrm{IN}}=-0.5 \mathrm{dBFS}$, Internal Reference, Clock $=65 \mathrm{MSPS}$, and Differential Input Range $=1 \mathrm{~V}_{\mathrm{PP}}$, unless otherwise noted.





## APPLICATION INFORMATION

## CONVERTER OPERATION

The ADS5122 is an 8-channel, simultaneous sampling ADC. Its low power and high sampling rate of 65MSPS is achieved using a state-of-the-art switched capacitor pipeline architecture built on an advanced low-voltage CMOS process. The ADS5122 primarily operates from a +1.8 V single supply. For additional interfacing flexibility, the digital I/O supply ( $\mathrm{DRV}_{\mathrm{DD}}$ ) can be set to either +1.8 V or +3.3 V . The ADC core of each channel consists of 10 pipeline stages. Each of the 10 stages produces one digital bit per stage. Both the rising and the falling clock edges are utilized to propagate the sample through the pipeline every half clock, for a total of five clock cycles. One and a half additional clock cycles are needed to pass the sample data through the digital error correction logic and the output latches. The total pipeline delay, or data latency, is therefore 6.5 clock cycles long. Since a common clock controls the timing of all eight channels, the analog signal is sampled at the same time, as well as the data on the parallel ports that become updated simultaneously.

## INPUT IMPEDANCE

Due to the switched capacitor input, the input impedance of the ADS5122 is effectively capacitive, and the driving source needs to provide sufficient slew current to charge and discharge the input sampling capacitor. The input impedance of the ADS5122 is also a function of the sampling rate. As the sampling frequency increases, the input impedance decreases at a linear rate of $1 / \mathrm{fs}$. For most applications, this does not represent a limitation since the impedance remains relatively high, for example, approximately $20 \mathrm{k} \Omega$ at the max sampling rate of 65MSPS. For applications using an op amp to drive the ADC, it is recommended that a series resistor, typically $10 \Omega$ to $50 \Omega$, be added between the amplifier output and the converter inputs. This will isolate the converter's capacitive input from the driver and avoid potential gain peaking, or instability.

## INPUT BIASING

The ADS5122 operates from a single +1.8 V analog supply, and requires each of the analog inputs (AIN+, AIN-) to be externally biased by a suitable common-mode voltage. For example, with a common-mode voltage of +1 V , the $1 \mathrm{~V}_{\mathrm{PP}}$ fullscale, differential input signal will swing symmetrically around +1 V , or between 0.75 V and 1.25 V . This is determined by the two reference voltages, the top reference (REFT), and the bottom reference (REFB). Typically, the input common-mode level is related to the reference voltages and defined as (REFT + REFB)/2. This reference mid-point is provided at the common-mode level output (CML) pin and can directly be used for input biasing purposes. The voltage at CML will assume the mid-point for either internal or external reference
operation. In any case, it is recommended to bypass the CML pin with a ceramic $0.1 \mu \mathrm{~F}$ capacitor.

## DRIVING THE ANALOG INPUTS

## Differential versus Single-Ended

The analog input of the ADS5122 allows it to be driven either single-ended or differentially. Differential operation of the ADS5122 requires an input signal that consists of an inphase and a $180^{\circ}$ out-of-phase part simultaneously applied to the inputs (AIN+, AIN-). The full-scale input range of the ADS5122 is defined by the reference voltages according to $F S R=2 \times$ (REFT - REFB). For a typical $1 V_{\text {PP }}$ range, the differential input configuration only requires each input to see a signal swing of $0.5 \mathrm{~V}_{\mathrm{Pp}}$. Operating the converter in singleended configuration requires the full $1 \mathrm{~V}_{\mathrm{PP}}$ swing applied to the chosen input. The differential operation offers a number of advantages, which in most applications will be instrumental in achieving the best dynamic performance of the ADS5122:

- Signal swing is half that required for the single-ended operation and is therefore less demanding to achieve while maintaining good linearity performance from the signal source.
- Reduced signal swing allows for more headroom of the interface circuitry and therefore a wider selection of the best suitable driver op amp.
- Even-order harmonics are minimized.
- Improved noise immunity based on the converter's com-mon-mode input rejection.

For the single-ended mode, the signal is applied to one of the inputs while the other input is biased with a DC voltage to the required common-mode level. Both inputs are identical in terms of their impedance and performance. Applying the signal to the complementary input (AIN-) instead of the AIN+ input, however, will invert the orientation of the input signal relative to the output code. This could be helpful, for example, if the input driver operates in inverting mode using input AIN- as the signal input will restore the phase of the signal to its original orientation.

## INPUT DRIVER CONFIGURATIONS

## Transformer-Coupled Interface

If the application requires a signal conversion from a singleended source to drive the ADS5122 differentially, an RFtransformer might be a good solution. The selected transformer must have a center tap in order to apply the commonmode DC voltage necessary to bias the converter inputs. ACgrounding the center tap will generate the differential signal swing across the secondary winding. Consider a step-up transformer to take advantage of signal amplification without the introduction of another noise source. Furthermore, the reduced signal swing from the source may lead to an improved distortion performance.

The differential input configuration may provide a noticeable advantage of achieving good SFDR performance over a wide range of input frequencies. In this mode, both inputs (AIN+ and AIN-) of the ADS5122 see matched impedances. Figure 1 shows the schematic for the suggested transformercoupled interface circuit. The component values of the R-C low-pass may be optimized depending on the desired roll-off frequency.

## Single-Ended, AC-Coupled Driver

The circuit of Figure 2 shows an example for driving the inputs of the ADS5122 in a single-ended configuration. The signal is AC-coupled between the driver amplifier and the converter input (AIN+). This allows for setting the required common-mode voltages for the ADC and op amp separately. The single-supply op amp is biased at mid-supply by two resistors connected at its noninverting input. Connecting each input to the CML pin provides the required commonmode voltage for the inputs of the ADS5122. Here, two resistors of equal value ensure that the inputs see closely
matched source impedances. If the op amp features a disable function, it could be easily tied together with the power-down pin of the ADS5122 channel ( $\overline{\mathrm{STBY}}$ ). In the circuit example depicted in Figure 2, the OPA355 EN pin is directly connected to the $\overline{\text { STBY }}$ pin to allow for a power-down mode of the entire circuit. Other suitable op amps for singlesupply driver applications include the OPA634, OPA635, or OPA690, for example.

## DC-Coupled Interface with Differential Amplifier

Differential input/output amplifiers can simplify the driver circuit for applications requiring input DC-coupling. Flexible in their configurations, such amplifiers can be used for singleended to differential conversion, allow for signal amplification, and also for filtering prior to the ADC. See Figure 3 for one possible circuit implementation using the THS4130 amplifier. Here, the amplifier operates with a gain of +1 . The common- mode voltage available at the CML pin can be conveniently connected to the amplifier VOCM pin to set the required input bias for the ADS5122.


FIGURE 1. Converting a Single-Ended Input Signal into a Differential Signal Using an RF-Transformer.


FIGURE 2. Single-Ended, AC-Coupled Driver Configuration for Single Supply.


FIGURE 3. DC-Coupled Interface Using Diferential I/O Amplifier THS4130.

## REFERENCE OPERATION

For proper operation of the ADS5122 and its reference, an external $4.42 \mathrm{k} \Omega$ resistor must be connected from the IREFR pin to analog ground (AGND), as shown in Figure 4. While a $1 \%$ resistor tolerance is adequate, deviating from this resistor value will cause altered and degraded performance.
To ensure proper operation with any reference configuration, it is necessary to provide solid bypassing at all reference pins in order to keep the clock feedthrough to a minimum. Figure 4 shows the recommended decoupling scheme. Good performance can be obtained using $0.1 \mu \mathrm{~F}$ low inductance ceramic capacitors. Adding tantalum capacitors $(1 \mu \mathrm{~F}$ to $10 \mu \mathrm{~F})$ may lead to a performance improvement, depending on the application. All bypassing capacitors should be located as close as possible to their respective pins.

## INTERNAL REFERENCE

The internal reference circuit of the ADS5122 consists of a bandgap voltage reference, the drivers for the top and bottom reference, and the resistive reference ladder. The corresponding reference pins are REFT, REFB, CML, IREFR, BG, and PDREF. In order to enable the internal reference, PDREF must be at a logic LOW $(=0)$ level. In addition, the bandgap pin (BG) should be decoupled with a $0.1 \mu \mathrm{~F}$ capacitor. The reference circuit provides the reference voltages to each of the eight channels.
The reference buffers can be utilized to supply up to 1 mA (sink and source) to an external circuitry. The CML pin represents the mid-point of the internal resistor ladder and is an unbuffered node. Loading of this pin should be avoided, as it will lead to degradation of the converter linearity.

## USING EXTERNAL REFERENCES

For even more design flexibility, the internal reference can be disabled and an external reference voltage used. The utilization of an external reference may be considered for applications requiring higher accuracy or improved temperature performance. Especially in multi-channel applications, the use of a common external reference has the benefit of obtaining better matching of the full-scale range between converters.
Setting the ADS5122 for external reference mode requires taking the PDREF pin HIGH. In addition, pins BG and REFT must be connected together (see Figure 5). The commonmode voltage at the CML pin will be maintained at approximately the mid-point of the applied reference voltages, according to $\mathrm{CML} \approx(\mathrm{VREFT}-\mathrm{VREFB}) / 2$. The internal buffer amplifiers for REFT and REFB are disabled when the


FIGURE 4. Internal Reference; Recommended Configuration and Bypassing.

ADS5122 operates in the external reference mode. The external reference circuit must be designed to drive the internal reference ladder ( $80 \Omega$ ) located between the REFT and REFB pins. For example, setting REFT $=+1.25 \mathrm{~V}$ and REFB $=+0.75 \mathrm{~V}$ will require a current drive capability of at least $0.5 \mathrm{~V} / 80 \Omega=6.25 \mathrm{~mA}$. The external references can vary as long as the value of the external top reference $\left(\mathrm{REFT}_{\text {EXT }}\right)$ stays within the range of +1.15 V to +1.35 V , and the external bottom reference ( $\mathrm{REFB}_{\mathrm{EXT}}$ ) stays within +0.65 V to +0.85 V (as shown in Figure 6).

## DIGITAL INPUTS AND OUTPUTS Clock Input

The clock input is designed to operate with +1.8 V or +3.3 V CMOS logic levels. The clock circuitry is internally connected to the DRV ${ }_{D D}$ supply. Therefore, the input HIGH and LOW levels will vary depending on the applied $D R V_{D D}$ supply; see DC Characteristics tables. Since both edges of the clock are used in this pipeline ADC, the ideal clock should be a squarewave logic signal with a $50 \%$ duty-cycle
Since this condition cannot always easily be met, the ADS5122 features an internal clock conditioning circuitry that can be activated through the duty-cycle adjust pin (DCASEL).

The DCASEL pin is a logic input, with its logic levels related to the $\mathrm{DV}_{\mathrm{DD}}$ supply ( +1.8 V only):
a) DCASEL = LOW (GND); in this mode the clock conditioning circuitry is disabled. Use this setting if the applied clock signal is a square-wave clock with a duty cycle of $50 \%$, or if the duty cycle stays within a range of $48 \%$ to 52\%.
b) DCASEL $=\mathrm{HIGH}\left(D V_{D D}\right)$; in this mode the clock conditioning circuitry is enabled. Use this setting if the applied external clock signal is a square-wave clock that does not meet the criteria listed above, but has a duty cycle in the range of $30 \%$ to $70 \%$.

## MINIMUM SAMPLING RATE

The pipeline architecture of the ADS5122 uses a switched capacitor technique for the internal track-and-hold stages. With each clock cycle, charges representing the captured signal level are moved within the ADC pipeline core. The high sampling rate necessitates the use of very small capacitor values. In order to hold the droop errors low, the capacitors require a minimum refresh rate. To maintain full accuracy of the acquired sample charge, the sampling clock of the ADS5122 should not be lower than the specified minimum of 5MSPS.


FIGURE 5. External Reference; Recommended Configuration and Bypassing.


FIGURE 6. Circuit Example of an External Circuit Using a Single-Supply, Low-Power, Dual Op Amp (OPA2234).

## DATA OUTPUT FORMAT

The output data format of the ADS5122 is a positive Straight Offset Binary (SOB) code. Tables I and II show output coding of a single-ended and differential signal. For all data output channels, the MSBs are located at the D9x pins.

| SINGLE-ENDED INPUT <br> (AIN- = CML) | STRAIGHT OFFSET BINARY <br> (SOB) |
| :--- | :---: |
| +FS - 1LSB (AIN+ = CML + FSR/2) | 1111111111 |
| +1/2 FS | 1100000000 |
| Bipolar Zero (AIN+ = CML) | 1000000000 |
| -1/2 FS | 0100000000 |
| -FS (AIN+ = CML - FSR/2) | 0000000000 |

TABLE I. Coding Table for Single-Ended Input Configuration with Input AIN- Tied to the Common-Mode Voltage (CML).

| DIFFERENTIAL INPUT | STRAIGHT OFFSET BINARY <br> (SOB) |
| :--- | :---: |
| + FS $-1 \mathrm{LSB}(\mathrm{AIN}+=$ REFT, AIN- = REFB) | 1111111111 |
| +1/2 FS | 1100000000 |
| Bipolar Zero (AIN+ = AIN- = CML) | 1000000000 |
| -1/2 FS | 0100000000 |
| -FS (AIN+ = REFB, AIN- = REFT) | 0000000000 |

TABLE II. Coding Table for Differential Input Configuration and $1 \mathrm{~V}_{\text {PP }}$ Full-Scale Range.

## DIGITAL OUTPUT LOADING

Minimizing the capacitive loading on the digital outputs is very important in achieving the best performance. The total load capacitance is typically made up of two sources: the next stage input capacitance, and the parasitic/pc-board capacitance. It is recommended to keep the total capacitive loading on the data lines as low as possible ( $\leq 20 \mathrm{pF}$ ). Higher capacitive loading will cause larger dynamic currents as the digital outputs are dynamic states. High current surges may cause feedback into the analog portion of the ADS5122 and affect the performance. If necessary, external buffers or latches close to the converter output pins may be used to minimize the capacitive loading. A suggested device is the SN74AVC16827 (20-bit buffer/driver), a member of the 'Advanced Very Low Voltage CMOS' logic family (AVC). Using such a logic device can also provide the added benefit of isolating the ADS5122 from any digital noise activities on the bus coupling back high-frequency noise. Some applications may also benefit from the use of series resistors $(\leq 100 \Omega)$ in the data lines. This will provide a current limit and reduce any existing over- or undershoot.

## OUTPUT ENABLE

The ADS5122 provides one output enable pin ( $\overline{\mathrm{OE} \text { ) that }}$ controls the digital outputs of all channels simultaneously. A LOW $(\mathrm{L}=0)$ level on the $\overline{\mathrm{OE}}$ pin will have all channels active and the converter in normal operation. Taking the $\overline{\mathrm{OE}}$ pin HIGH ( $\mathrm{H}=1$ ) will disable or tri-state the outputs of all
channels. Note that the $\overline{\mathrm{OE}}$ pin has no internal pull-up resistor and therefore requires a defined potential to be applied. The timing relations between $\overline{\mathrm{OE}}$ and the output bus enable/disable times are shown in the Timing Diagram.

## POWER-UP SEQUENCE

Ideally, the three main power supplies for the ADS5122 should be applied and ramped up simultaneously. If this cannot be ensured, the following power-up sequence is recommended:

1. $A V_{D D}(+1.8$ typ $)$
2. $D V_{D D}(+1.8$ typ)
3. $\mathrm{DRV}_{\mathrm{DD}}$ (+3.3 typ)

The clock signal should also be applied with proper logic levels during power-up of the ADS5122. Deviating from this power-up sequence may cause the device to enter a mode such that the digital outputs do not approach the full specified output levels.

## POWER-DOWN (STANDBY)

The ADS5122 is equipped with a power-down function for each of the eight channels. Labeled as $\overline{\text { STBY }}$ pins, the channel is in normal operating mode when the STBY pin is connected to logic high ( $\mathrm{H}=1$ ). The selected ADC channel will be in a power-down mode if the corresponding $\overline{\text { STBY }}$ pin is connected to logic LOW $(\mathrm{L}=0)$. The logic levels for the $\overline{\text { STBY }}$ pins are dependent on the DRV $_{\text {DD }}$ supply. The powerdown function controls internal biasing nodes, and as a consequence, any data present in the pipeline of the converter will become invalid. This is independent of whether the clock remains applied during power-down or not. Following a power-up, new valid data will become available after a minimum of seven clock cycles. As a note, the operation of the $\overline{\text { STBY }}$ pins is not intended for the use of dynamically multiplexing between the eight channels of the ADS5122.

## DIGITAL OUTPUT DRIVER SUPPLY, DRV ${ }_{D D}$

The ADS5122 uses a dedicated supply connection for the output logic drivers, $D R V_{D D}$, along with its digital driver ground connections, labeled DRGND.
Setting the voltage at $\mathrm{DRV}_{\mathrm{DD}}$ to either +3.3 V or +1.8 V alse sets the output logic levels accordingly, allowing the ADS5122 to directly interface to a selected logic family. The output stages are designed to supply sufficient current to drive a variety of logic families. However, it is recommended to use the ADS5122 with a +1.8 V driver supply. This will lower the power dissipation in the output stages due to the lower output swing and reduce current glitches on the supply lines, which otherwise may affect the AC performance of the converter. In some applications it might be advantageous to decouple the DRV $V_{D D}$ supply with additional capacitors or a pi-filter.

## GROUNDING AND DECOUPLING

Proper grounding and bypassing, short lead length, and the use of ground planes are particularly important for highfrequency designs. Multilayer pc-boards are recommended
for best performance since they offer distinct advantages such as minimizing ground impedance, separation of signal layers by ground layers, etc. The ADS5122 should be treated as an analog component. Whenever possible, the supply pins should be powered by the analog supply. This will ensure the most consistent results, since digital supply lines often carry high levels of noise which otherwise would be coupled into the converter and degrade the achievable performance. The ground pins should directly connect to an analog ground plane covering the pc-board area under the converter. While designing the layout it is important to keep the analog signal traces separated from any digital line to prevent noise coupling onto the analog signal path. Due to its high sampling rate, the ADS5122 generates high-frequency current transients and noise (clock feedthrough) that are fed back into the supply and reference lines. This requires that all supply and reference pins are sufficiently bypassed. In most cases $0.1 \mu \mathrm{~F}$ ceramic chip capacitors at each pin are adequate to keep the impedance low over a wide frequency range. Their effectiveness depends largely on the proximity to the individual supply pin. Therefore, they should be located as close as possible to the supply pins. In addition, a larger bipolar capacitor ( $1 \mu \mathrm{~F}$ to $22 \mu \mathrm{~F}$ ) should be placed on the pc-board in proximity to the converter circuit.

## LAYOUT OF THE PCB WITH A MICROSTAR BGA PACKAGE

The ADS5122 is housed in a polyimide film-based chipscale package (CSP). Like most CSPs, solder alloy balls are used as the interconnect between the package substrate and the board on which the package is soldered. For detailed information regarding these packages, please refer to literature number SSYZ015B, MicroStar BGA Packaging Reference Guide, which addresses the specific considerations required when integrating a MicroStar BGA package into the PCB design. This document can be found at:
http://www-s.ti.com/sc/psheets/ssyz015b/ssyz015b.pdf

## TERMINOLOGY

## ANALOG BANDWIDTH

The analog input frequency at which the spectral power of the fundamental frequency (as determined by the FFT analysis) is reduced by 3 dB .

## APERTURE DELAY

The delay between the $50 \%$ point of the rising edge of the clock and the instant at which the analog input is sampled.

## APERTURE UNCERTAINTY (JITTER)

The sample-to-sample variation in aperture delay.

## EFFECTIVE NUMBER OF BITS (ENOB)

The ENOB is calculated from the measured SINAD based on the equation:

$$
\mathrm{ENOB}=\left(\frac{\mathrm{SINAD}-1.76 \mathrm{~dB}}{6.02}\right)
$$

## EFFECTIVE RESOLUTION BANDWIDTH

The maximum analog input frequency at which the SINAD is decreased by 3 dB or the ENOB by half a bit.

## GAIN ERROR

Gain Error is the deviation of the actual difference between first and last code transitions and the ideal difference between first and last code transitions.

## GAIN MATCHING

Variation in Gain Error between adjacent channels.

## 2ND-HARMONIC DISTORTION

The ratio of the rms signal amplitude to the rms value of the 2nd-harmonic component, reported in dBc.

## 3RD-HARMONIC DISTORTION

The ratio of the rms signal amplitude to the rms value of the 3rd-harmonic component, reported in dBc.

## INTERMODULATION DISTORTION (IMD)

The 2-tone IMD is the ratio expressed in decibels of either input tone to the worst 3rd-order (or higher) Intermodulation products. The individual input tone levels are at -6.5 dB fullscale, and their envelope is at -0.5 dB full-scale.

## OFFSET ERROR (ZERO-SCALE ERROR)

The first transition should occur for an analog value 1/2 LSB above negative full-scale. Offset error is defined as the deviation of the actual transition from that point.

## OFFSET MATCHING

The change in offset error between adjacent channels.

## POWER-SUPPLY REJECTION RATIO (PSRR)

The ratio of a change in input offset voltage to a change in power-supply voltage.

## SIGNAL-TO-NOISE AND DISTORTION (SINAD)

The ratio of the rms signal amplitude (set 0.5 dB below fullscale) to the rms value of the sum all other spectral components, including harmonics but excluding DC.

## SIGNAL-TO-NOISE RATIO (WITHOUT HARMONICS)

The ratio of the rms signal amplitude (set 0.5 dB below fullscale) to the rms value of the sum of all other spectral components, excluding the first five harmonics and DC.

## SPURIOUS-FREE DYNAMIC RANGE (SFDR)

The ratio of the rms signal amplitude to the rms value of the peak spurious spectral component. The peak spurious component may or may not be a harmonic. May be reported in dBc (i.e., degrades as signal level is lowered), or dBFS (always related back to converter full-scale).

## PACKAGING INFORMATION

| Orderable Device | Status $^{(1)}$ | Package <br> Type | Package <br> Drawing | Pins Package <br> Qty | Eco Plan ${ }^{(2)}$ | Lead/Ball Finish | MSL Peak Temp ${ }^{(3)}$ |  |
| :---: | :---: | :---: | :---: | :---: | :---: | :---: | :---: | :---: |
| ADS5122CGHK | ACTIVE | BGA | GHK | 257 | 90 | None | SNPB | Level-3-220C-168 HR |

${ }^{(1)}$ The marketing status values are defined as follows:
ACTIVE: Product device recommended for new designs.
LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.
NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.
PREVIEW: Device has been announced but is not in production. Samples may or may not be available.
OBSOLETE: TI has discontinued the production of the device.
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${ }^{(3)}$ MSL, Peak Temp. -- The Moisture Sensitivity Level rating according to the JEDECindustry standard classifications, and peak solder temperature.

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GHK (S-PBGA-N257)
PLASTIC BALL GRID ARRAY


NOTES: A. All linear dimensions are in millimeters.
B. This drawing is subject to change without notice.
C. MicroStar BGA ${ }^{\text {M4 }}$ configuration.

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Mailing Address: Texas Instruments<br>Post Office Box 655303 Dallas, Texas 75265

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